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(54) **Title:** METHOD AND SYSTEM FOR MANUFACTURING INTEGRATED CIRCUIT

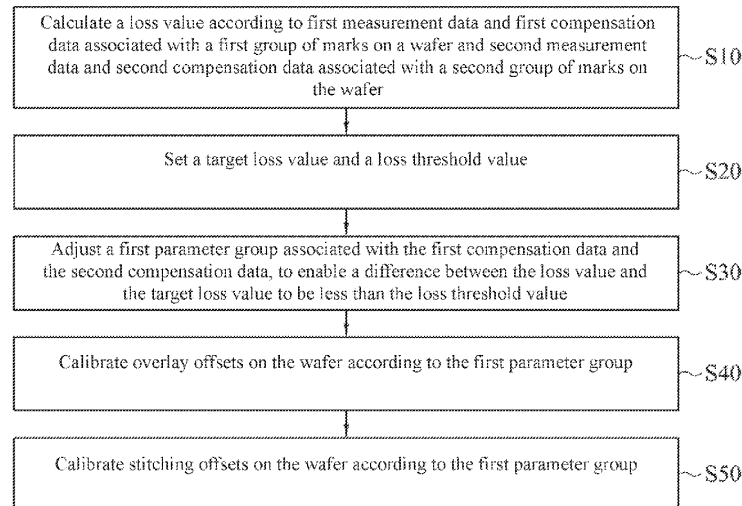


FIG. 4

(57) **Abstract:** The method for manufacturing an integrated circuit includes: calculating a loss value according to first measurement data and first compensation data associated with a first group of marks on a wafer and second measurement data and second compensation data associated with a second group of marks on the wafer; and adjusting a first parameter set associated with the first compensation data and the second compensation data such that a difference between the loss value and a target loss value to be less than a loss threshold.

[Continued on next page]

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